



## **Dr. Kwang-Seong Choi**

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Kwang-Seong Choi received the B.S. degree from Hanyang University, Seoul, Republic of Korea, and the M.S. and Ph.D. degrees from Korea Advanced Institute of Science and Technology (KAIST), Daejeon, Republic of Korea.

From 1995 to 2001, he was with Hynix Semiconductor Ltd., Incheon, Republic of Korea, where he was involved in the development of chip scale packages, package-on-packages, and high-speed electronic packages for DDR, Rambus, and RF devices. Since 2001, he has been with Electronics and Telecommunications Research Institute (ETRI), Daejeon, Republic of Korea, where he is currently working as a director and research fellow. His research interest includes the development of the packaging materials and processes for 3D ICs with through silicon via (TSV), next-generation displays, and large array of thin devices.